

**REMARKS**

Claims 11-12 and 14-17 are pending in this application, of which claims 11 and 16 have been amended. No new claims have been added.

The Examiner has objected to the drawings for failing to show the openings in the solder resist for the solder balls as recited in claim 11.

Accordingly, a corrected print of Fig. 4 showing these openings is attached hereto. Page 7, lines 4-5 of the specification have been amended to disclose "... bump 7 projects outwardly from the solder resist layer 3b that covers the surface of the circuit substrate 6 though a hole 7a in the solder resist layer 3b.

Claims 11, 12 and 14-17 stand rejected under 35 USC §102(e) as anticipated by U.S. Patent 6,114,753 to Nagai et al. (hereinafter "**Nagai et al.**").

Applicants respectfully traverse this rejection.

**Nagai et al.** discloses a semiconductor device having a buffer body for absorbing the difference of thermal expansion between the mounting substrate and the semiconductor element in a semiconductor package structure. An organic material is used for the mounting substrate. A film material is used as the body for buffering the thermal stress generated by the difference in thermal expansion between the mounting substrate and the semiconductor element.

Figs. 6.1, 6.2 and 6.3 show solder balls 6.5 attached to a circuit tape 6.1, where the circuit tape is connected to semiconductor element 6.3 via connecting leads 6.8. There is no disclosure or suggestion in **Nagai et al.** that the solder balls 6.5 extend through a hole through the circuit tape 6.1, as do the solder bumps (spherical electrodes 7) which contact circuit substrate 6 through

holes in solder resist layer 3b in the present invention. The circuit tape 6.1 in Nagai et al. has no holes for any such purpose.

It should be noted that the semiconductor device of the present invention is manufactured by dicing the chip together with a potting resin or resin sidewall cover thereon and thus has an inherent feature that the potting resin or the resin sidewall cover forms a flat surface formed by the dicing blade.

In contrast, Nagai et al. fails to teach this feature of the present invention because of the different manufacturing process used, and claims 11 and 16 have been amended to recite this feature.

Thus, the 35 USC §102(c) rejection should be reconsidered and withdrawn.

In view of the aforementioned amendments and accompanying remarks, claims 11-12 and 14-17, as amended, are in condition for allowance, which action, at an early date, is requested.

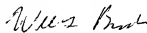
If, for any reason, it is felt that this application is not now in condition for allowance, the Examiner is requested to contact Applicants' undersigned attorney at the telephone number indicated below to arrange for an interview to expedite the disposition of this case.

U. S. Patent Application Serial No. 09 768,174

In the event that this paper is not timely filed, Applicants respectfully petition for an appropriate extension of time. Please charge any fees for such an extension of time and any other fees which may be due with respect to this paper, to Deposit Account No. 01-2340.

Respectfully submitted,

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